Supplementary Information

In situ TEM nanoindentation-induced new nanostructure in

cadmium zinc telluride

Dongdong Liu,^a Zhenyu Zhang,^{*a} Leilei Chen,^a Dong Wang,^b Junfeng Cui,^a Keke Chang,^c Dongming Guo^a

^aKey Laboratory for Precision and Non-Traditional Machining Technology of Ministry of Education, Dalian University of Technology, Dalian 116024, China. E-mail: zzy@dlut.edu.cn ^bBeijing Spacecrafts Manufacturing Factory Co., Ltd., China Academy of Space Technology, Beijing 100094, China.

^cKey Laboratory of Marine Materials and Related Technologies, Ningbo Institute of Materials Technology and Engineering, Chinese Academy of Sciences, Ningbo 315201, China.



Figure S1 Optical images on the surface of (a) received, (b) lapped, and (c) CMP polished CZT wafers.



Figure S2 Surface roughness and morphologies on CZT wafers (a) lapped by an abrasive paper with a mesh size of 2000, and (b) polished by CMP.



Figure S3 (a) XRD and (b) PL spectra on the polished surface of CZT. Inset in (a) showing the photograph of a CZT wafer after CMP.



Figure S4 (a) TEM image of a specimen after thinning by electron beam in FIB prior to *in situ* nanoindentation at low magnification, and (b) its magnified area taken from a green square in (a). Inset in (b) showing the corresponding SAED pattern.